Stefan JOHANSSON et al.

R E M A R K S

The above changes in the claims merely place this national phase application in the same condition as it was during the international phase, with the multiple dependencies being removed.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE".

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

The claims have been amended as follows:

3. (Amended) The transducer microsystem according to claim 1~~ or 2~~, characterised in that said flexible printed circuit board (10) has an elastic deformation, whereby said flexible printed circuit board (10) forms a general support for internal (30,32) and external forces.

4. (Amended) The transducer microsystem according to claim 1, ~~2 or 3,~~ characterised in that said flexible printed circuit board (10) is elastically deformed to apply an elastic contact force (30,32) to at least one of said components (22) of said electromechanical transducer, forming a mechanical contact.

5. (Amended) The transducer microsystem according to ~~any of the preceding~~ claim~~s~~ **1**, characterised by electrical components (24) and/or optical components attached to said flexible printed circuit board (10).

7. (Amended) The transducer microsystem according to ~~any of the~~ claim~~s~~ 3~~ to 6~~, characterised in that said elastic deformation comprises an elastic compression or tension substantially perpendicular to the surface of said flexible printed circuit board (10).

9. (Amended) The transducer microsystem according to ~~any of the~~ claim~~s~~ 3~~ to 8~~, characterised in that said

elastic deformation comprises an elastic deflection of at least a portion (19) of said flexible printed circuit board (10).

11. (Amended) The transducer microsystem according to claim 9~~ or 10~~, characterised in that a first component (22) of said electromechanical transducer is positioned in the path of said elastic deflection, whereby the resilience of said deflected flexible printed circuit board portion (19) applies a spring force on said first component (22) of said electromechanical transducer.

12. (Amended) The transducer microsystem according to ~~any of the preceding~~ claim~~s~~ **1**, characterised in that said flexible printed circuit board (10) constitutes a casing of said transducer microsystem.

13. (Amended) The transducer microsystem according to ~~any of the preceding~~ claim~~s~~ **1**, characterised in that said flexible printed circuit board (10) comprises polyimide material.

14. (Amended) The transducer microsystem according to ~~any of the preceding~~ claim~~s~~ **1**, characterised in that said flexible printed circuit board (10) is provided with geometrical structures (16, 18, 20; 32, 33, 34; 40, 42; 44, 46, 48), which are engagable to other ones of said geometri-

cal structures (16, 18, 20; 32, 33, 34; 40, 42; 44, 46, 48) and/or to other members of said transducer microsystem.

16. (Amended) The transducer microsystem according to claim 14~~ or 15~~, characterised in that said geometrical structures (16, 18, 20; 32, 33, 34; 40, 42; 44, 46, 48) comprise adjustable locking structures.

17. (Amended) A microelectromechanical motor, comprising a transducer microsystem according to ~~any of the preceding~~ claim~~s~~ **1**.

21. (Amended) The method of assembling a transducer microsystem according to claim 19~~ or 20~~, characterised by the further step of attaching electrical components (24) and/or optical components to said flexible printed circuit board (10).

22. (Amended) The method of assembling a transducer microsystem according to claim 19, ~~20 or 21,~~ characterised in that at least the major part of any steps of attaching components (22, 24, 26) to said flexible printed circuit are performed on a substantially flat flexible printed circuit board (10).

23. (Amended) The method of assembling a transducer microsystem according to ~~any of the~~ claim~~s~~ 19~~ to 22~~, characterised by the further step of providing said flexible printed circuit board (10) with geometrical structures (16,

18, 20; 32, 33, 34; 40, 42; 44, 46, 48), which are engagable to other ones of said geometrical structures (16, 18, 20; 32, 33, 34; 40, 42; 44, 46, 48) and/or to other member of said transducer microsystem.

26. (Amended) The method of assembling a transducer microsystem ~~according to any of the~~ claims ~~20 to 25~~, characterised in that said step of reshaping comprises at least one of the following steps;

elastically folding said flexible printed circuit (10);

elastically bending said flexible printed circuit (10); and

elastically tensing or compressing said flexible printed circuit (10) substantially perpendicular to its surface.